

S83	2	("6271792").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/03 18:59
S84	130	dielectric and ((adhesive melt\$4) near layer) and (radiat\$4 antenna) and antenna and patch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/03 20:05
S85	9	("5115217" "5155493" "5227749" "5444453" "5497164" "5583376" "5661494" "5712644" "5825334").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/03 19:50
S86	102	dielectric and ((adhesive melt\$4) near layer) and (radiat\$4 antenna) and antenna and patch and ground	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/03 20:09
S87	182	dielectric and ((adhesive melt\$4 bond\$3) near layer) and (radiat\$4 antenna) and antenna and patch and ground	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/03 20:10
S88	182	dielectric and ((adhesive melt\$4 bond\$3) near layer) and ((radiat\$4 adj3 element) antenna) and antenna and patch and ground	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/03 20:10
S89	113	dielectric and ((adhesive melt\$4 bond\$3) near layer) and ((radiat\$4 adj3 element) antenna) and (antenna near3 patch\$3) and ground	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/03 20:10
S90	11	("4790968" "5112726" "5538789" "5541366" "5733639" "5910354" "6197407" "6356245" "6366259" "6451441" "6518514").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/04 15:51
S91	491	(343/705).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/04 16:53
S92	164	S91 and ground	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 15:52

S93	1	S91 and ground and dielectric and ((adhesive melt\$4 bond\$3) near layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 16:02
S94	1	S91 and ground and (dielectric substrate) and ((adhesive melt\$4 bond\$3) near layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 16:17
S95	1	S91 and ground and (dielectric substrate) and ((adhesive adhesiv\$3 melt\$4 bond\$3) near layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 16:17
S96	20	S91 and ground and (dielectric substrate) and (adhesive adhesiv\$3 melt\$4 bond\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 16:54
S97	81	S91 and ground and (dielectric substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 11:28
S98	2	("6703114").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/05 13:51
S99	2	("6271792").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/05 13:51